



# Data Display Products®

## T-1<sup>3</sup>/<sub>4</sub> LEDs Low Profile, Non-Diffused

- Red, Amber, Yellow, Green
- Non-Diffused Tinted Encapsulation
- Luminous Intensities from 24 to 75 mcd

### Electro-Optical Characteristics @ T<sub>A</sub> = 25°C

Part Number	Color	Peak Wavelength λ <sub>pk</sub> (nm)	Luminous Intensity I <sub>v</sub> (mcd) @ I <sub>f</sub> =20mA Min/Typ	Viewing Angle 2θ <sub>1/2</sub> (deg)	Forward Voltage V <sub>f</sub> @ I <sub>f</sub> =20mA Typ/Max	Absolute Maximum Ratings @ T <sub>A</sub> = 25°C				
						Power Dissipation (mW)	Derating Factor (mW/°C)	Maximum Continuous Current (mA)	Peak Forward Current 5% Duty Cycle (mA)	Operating & Storage Temperature (°C)
180-ECR	RED	660	30/60	30	1.7/2.0	100	1.6	50	300	-30 / +85[2]
180-BCR	RED	635	24/36	45	2.2/3.0	135	1.8	30	90	-55 / +100
180-ECA	AMB	605	30/45	30	2.2/2.5	125	1.8	50	100	-30 / +85[2]
180-BCA	AMB	583	24/36	45	2.2/3.0	85	1.6[1]	20	60	-55 / +100
180-ECY	YEL	570	50/75	30	2.1/2.5	125	1.8	50	100	-30 / +85[2]
180-BCG	GRN	565	22/30	40	2.3/3.0	135	1.8	30	90	-55 / +100
180-ECG	GRN	555	16/24	30	2.1/2.5	125	1.8	50	100	-30 / +85[2]

[1] Derate from T<sub>A</sub> = 50°C.

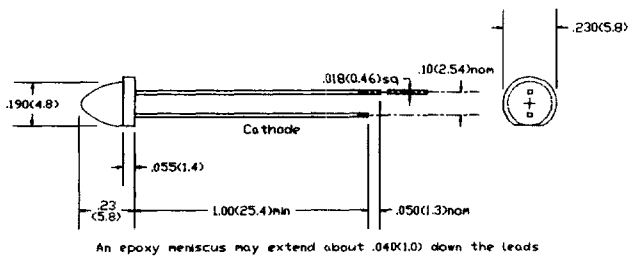
[2] Storage Temperature = -30/ +100°C.

Reverse Breakdown Voltage V<sub>r</sub>(I<sub>R</sub>=100μA)=5Vdc, E Series=4Vdc.  
LED Soldering Temperature=260°C (1/16" below package base for 5 seconds).

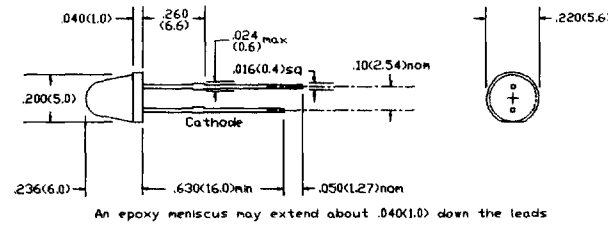
Color	λ <sub>pk</sub> (nm)	Chip Material
RED	660	GaAlAs
RED	635	GaAsP/GaP
AMB	583-605	GaAsP/GaP
YEL	570	GaP
GRN	555-565	GaP

**To Order:** Select one Part Number from the **SHADED** column in the table.

**Example:** 180-BCR (T-1<sup>3</sup>/<sub>4</sub> Low Profile, Non-Diffused B Series, RED)



Low Profile B Series



Low Profile E Series

All dimensions are in inches(mm)  
Tolerances: .xx"(x) ± .025"(.63) / .xxx"(xx) ± .010"(.25)  
Specifications are subject to change without notice.